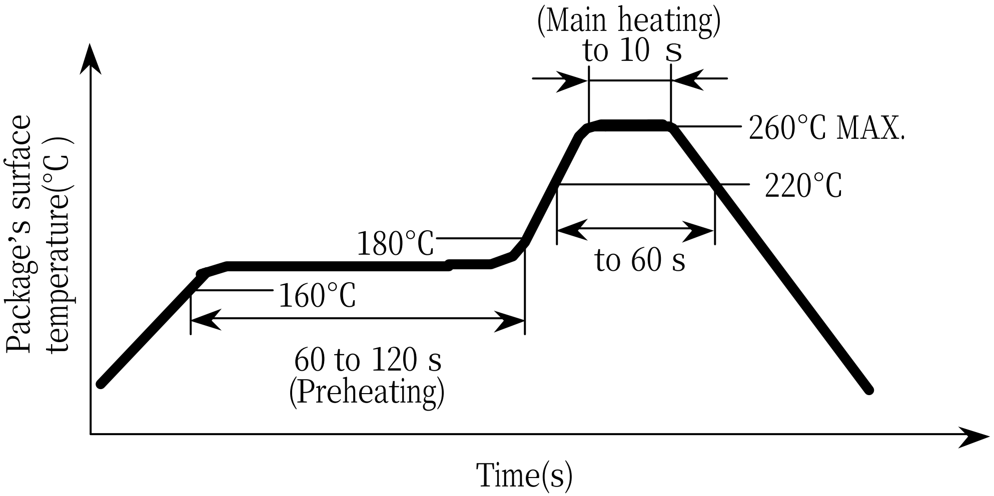
RECOMMENDED SOLDERING CONDITIONS
OF
INFRARED REFLOW
[INCLUDING CONVECTION, INFRARED/CONVECTION]

(IR60-00-3)

The following is recommended soldering conditions of infrared reflow.

Maximum temperature (Package's surface temperature) : 260°C or below
Time at maximum temperature : 10s or less
Time of temperature higher than 220°C : 60s or less
Preheating time at 160 to 180°C : 60 to 120s
Maximum number of reflow processes : 3 times
Maximum chlorine content of rosin flux (percentage mass) : 0.2 % or less



Infrared Reflow Temperature Profile